

**TECHNICAL MANUAL**

**ORGANIZATIONAL MAINTENANCE  
MANUAL:  
AUTOMATIC DATA  
PROCESSOR EQUIPMENT  
MAINTENANCE  
GUIDED MISSILE AIR DEFENSE SYSTEM AN/TSQ - 73**

This copy is a reprint which includes current pages from Changes 1  
Through 12.

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**HEADQUARTERS, DEPARTMENT OF THE ARMY  
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**ORGANIZATIONAL MAINTENANCE MANUAL: AUTOMATIC DATA PROCESSOR  
EQUIPMENT MAINTENANCE**

**GUIDED MISSILE AIR DEFENSE SYSTEM AN/TSQ-73**

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CHAPTER 1

INTRODUCTION

Section I. GENERAL

**1-1. Scope.** This manual contains organizational maintenance information for the Guided Missile Air Defense System AN/TSQ-73 Automatic Data Processor (ADP) equipment (fig. 1-1). This manual is for use by personnel responsible for maintaining the ADP equipment. Chapter 1 provides physical and technical characteristics. Chapter 2 provides a theory of operation. Chapter 3 provides maintenance and fault isolation. Chapter 4 provides removal and replacement instructions.

**1-2. Forms, Records, and Reports.** Refer to DA PAM 738-750 for the use and completion of all forms required for operating and maintaining the equipment.

**1-3. Destruction of Army Materiel to Prevent Enemy Use.** If capture of this equipment appears imminent, or if the equipment must be abandoned, it should be destroyed to prevent enemy use. Destruction procedures should be carried out only on orders from the cognizant authority. Refer to TM 43-0002-21 for procedures required for destruction of the equipment and related system materiel. Recorded tape transport cartridges and classified manuals are priority items requiring destruction.

**1-4. Reporting Equipment Publications Improvements.** Reporting of errors and omissions and recommendations by the individual user for improving this publication is encouraged. Reports should be submitted on DA Form 2028. Recommended Changes to Publications, and forwarded to: Commander, U.S. Army Missile Command, ATTN: AMSMI-LC-ME-P, Redstone Arsenal, Alabama 35898-5238.

**1-5. Reference.** Refer to List of Applicable Publications TM 9-1425-655-L for a list of related publications and reference documents.

**1-6. Abbreviations.** Refer to appendix A for a list of abbreviations used in this manual.

**1-7. Official Nomenclature.** AN/TSQ-73 system nomenclature associated with the equipment is listed in table 1-1. For further identification, cross-reference is provided for the common name used in this technical manual.

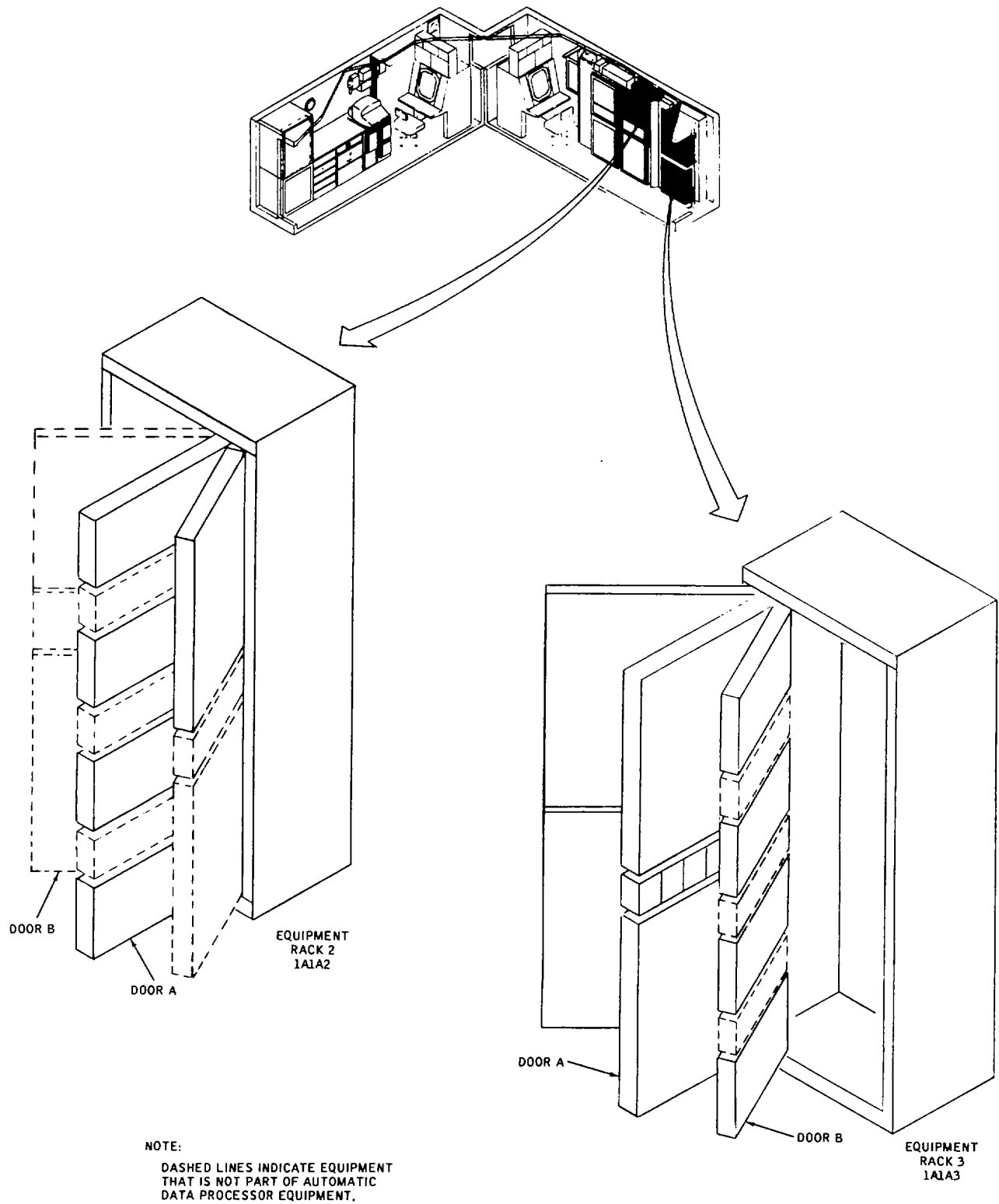
**1-8. General.** The ADP equipment for the AN/TSQ-73 system includes two Central Processing Units (CPUs), four 32K memory units, an Input/Output Unit (IOU), a buffer unit and 10 supporting power supplies. Part of the ADP equipment is the ADP status and control panel, which contains all of the indicators and controls required for operation of the ADP equipment. Peripheral devices used with the ADP equipment are the Keyboard Printer Unit (KPU), which provides manual access to the ADP during data processing, and the Magnetic Tape Units (MTUs), that function as bulk external memories and program input devices. These units combine to process radar and fire unit input data as required for the AN/TSQ73 system to perform its assigned mission of FU selection and weapon assignment.

**Table 1-1. AN,TSQ.73 Official Nomenclature**

Official nomenclature	Common name
Air Defense System, Guided Missile AN/TSQ-73	AN/TSQ-73 system (battalion configuration) AN/TSQ-73 system (brigade configuration)
Shelter. Electrical Equipment S-529/TSQ-73	System shelter (battalion configuration) System shelter (brigade configuration)
Console, Assault Fire Command, Guided Missile OJ-299/TSQ-73	Display console
Data Display Group OD-96/TSQ-73	Data Display Group (DDG)

**Table 1-1. AN/TSQ-73 Official Nomenclature  
-Continued**

Official nomenclature	Common name
Recorder-Reproducer, Guided Missile System, RD-449/TSQ-73	Magnetic Tape Unit (MTU)
Test Set, Electronic Circuit Plug-In Unit TS-3317/TSQ-73	Module Test Set (MTS)



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**Figure 1-1. Automatic Data Processor Equipment**

**Change 6 1-2.1/(1-2.2 blank)**